

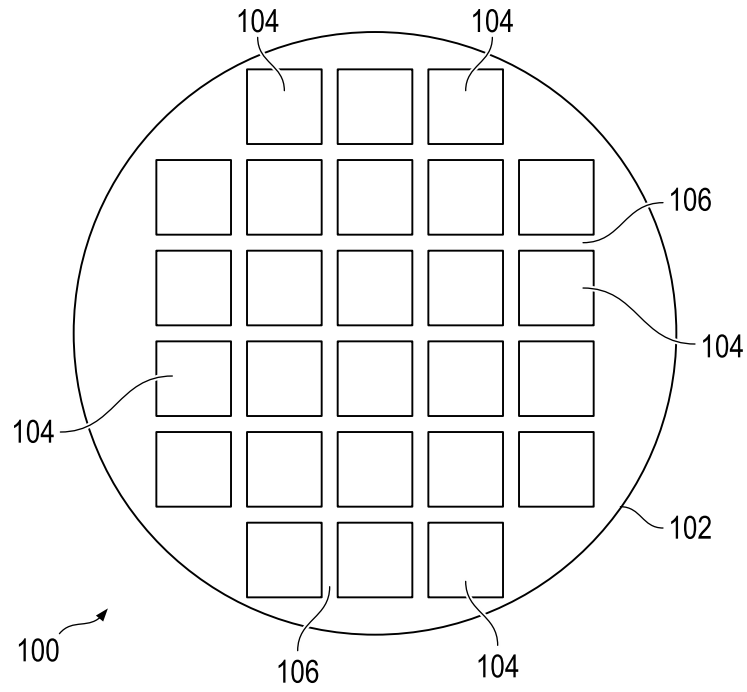


FIG. 1a

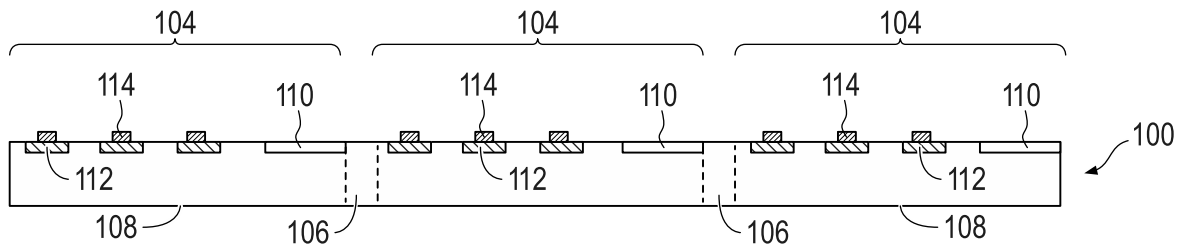


FIG. 1b

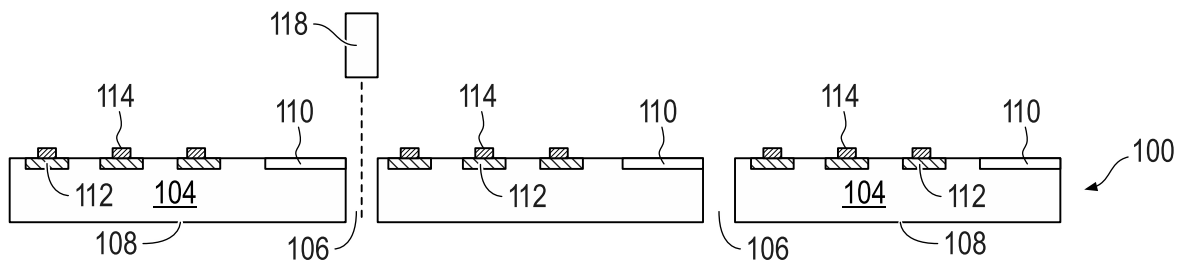


FIG. 1c

This cross-sectional view shows a substrate with layers 119a, 119b, 122, and 120. A top layer 140 is patterned into regions 124a and 124b. Regions 124a contain vias 130 and 132 that connect to the 122 layer. Region 124b contains a via 122 that connects to the 120 layer. Arrows 142 indicate downward forces or directions.

A cross-sectional view of a semiconductor device. The device consists of a substrate with layers 119a and 119b. A top layer 120 is formed on the substrate. The top layer 120 contains various patterns including 122, 124a, 126, 130, 132, 140, 142, 144, and 146. The patterns are arranged in a series of steps and recesses.

[illegible]

*FIG. 2d*

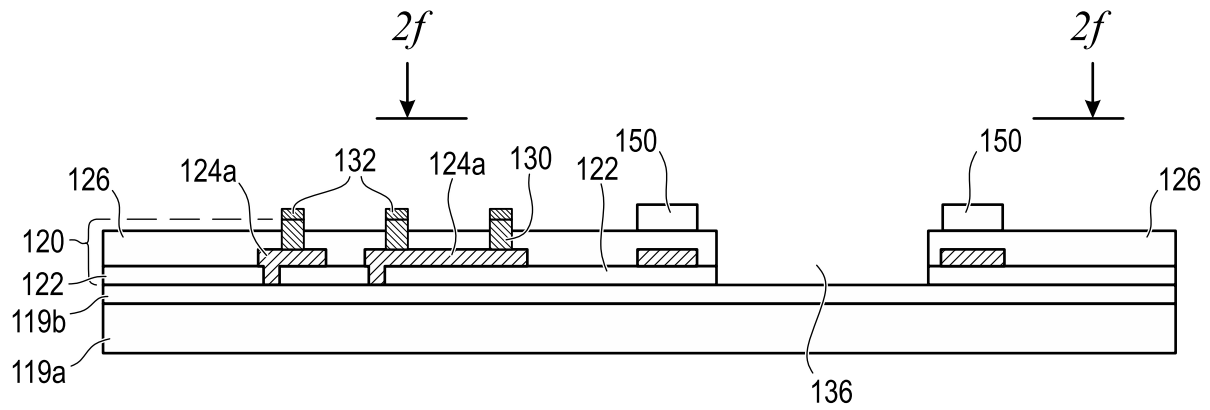


FIG. 2e

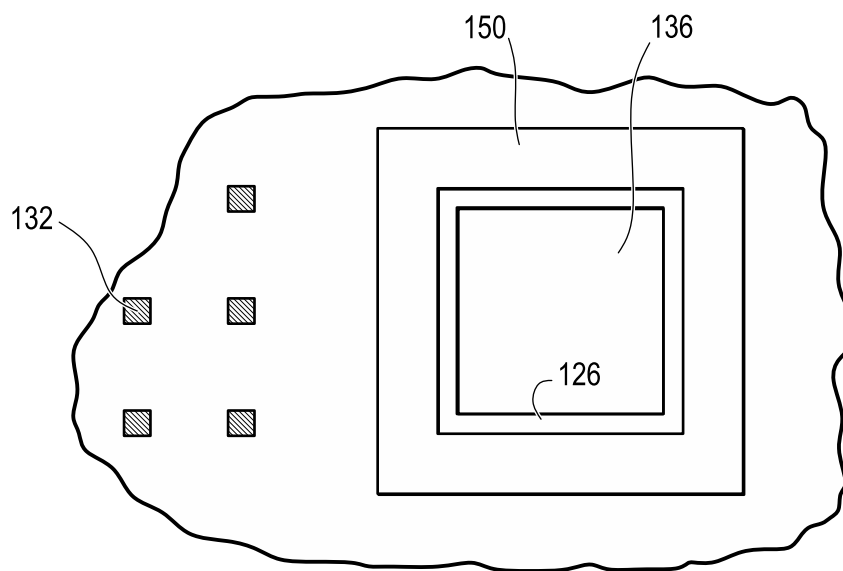


FIG. 2f

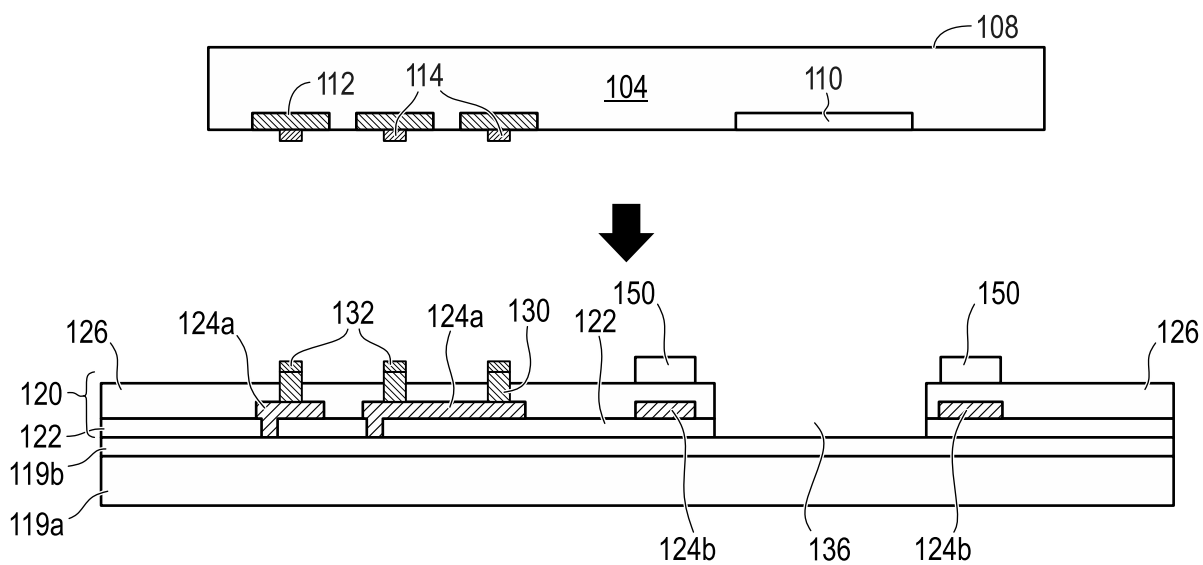


FIG. 2g

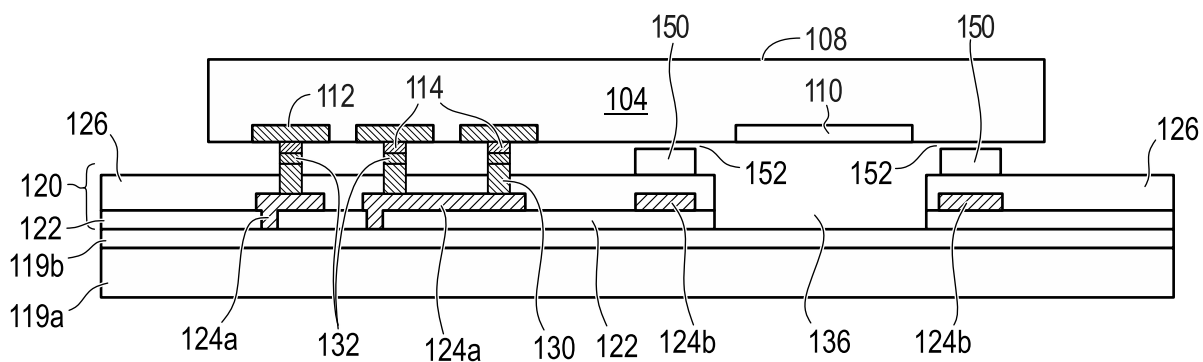


FIG. 2h

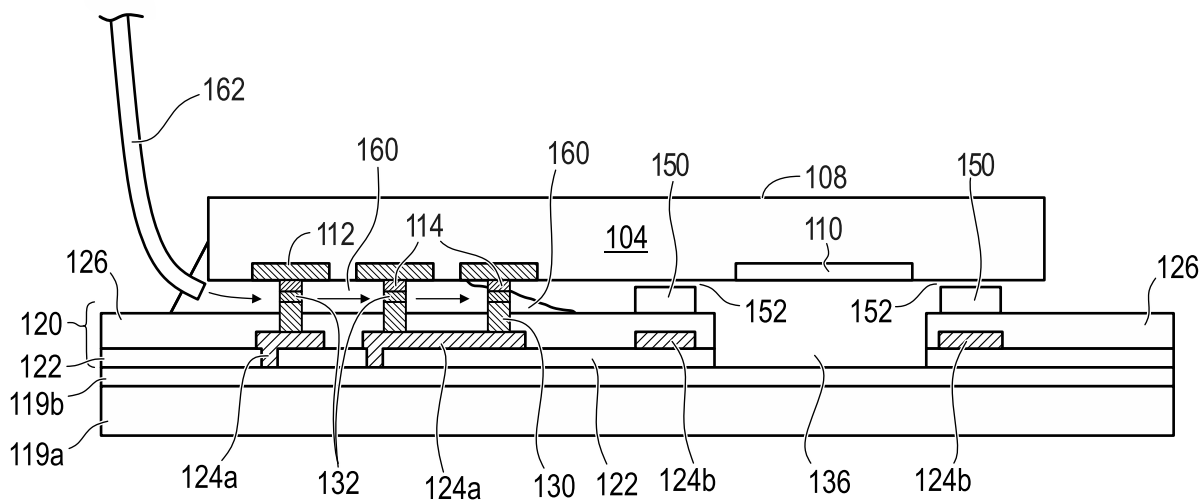


FIG. 2i

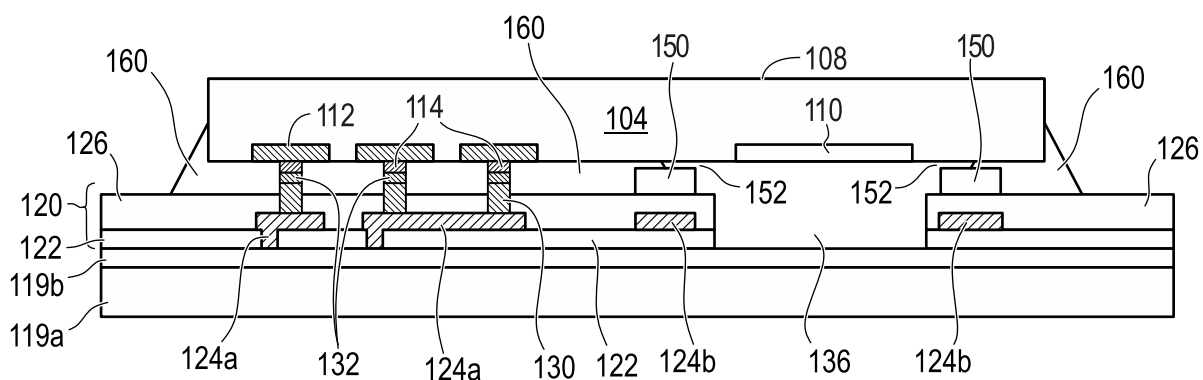
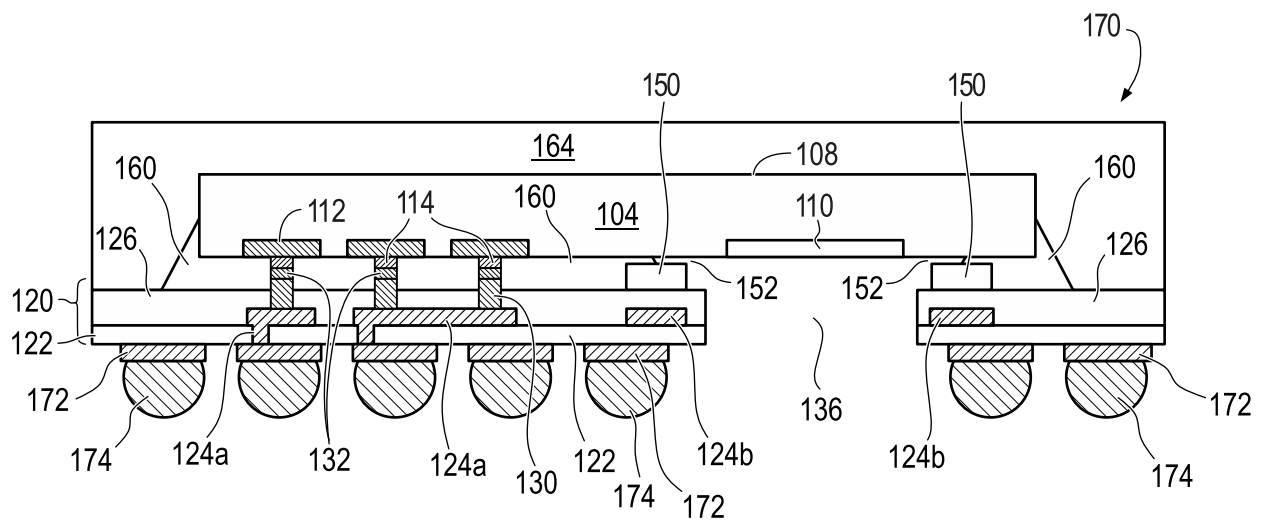


FIG. 2j



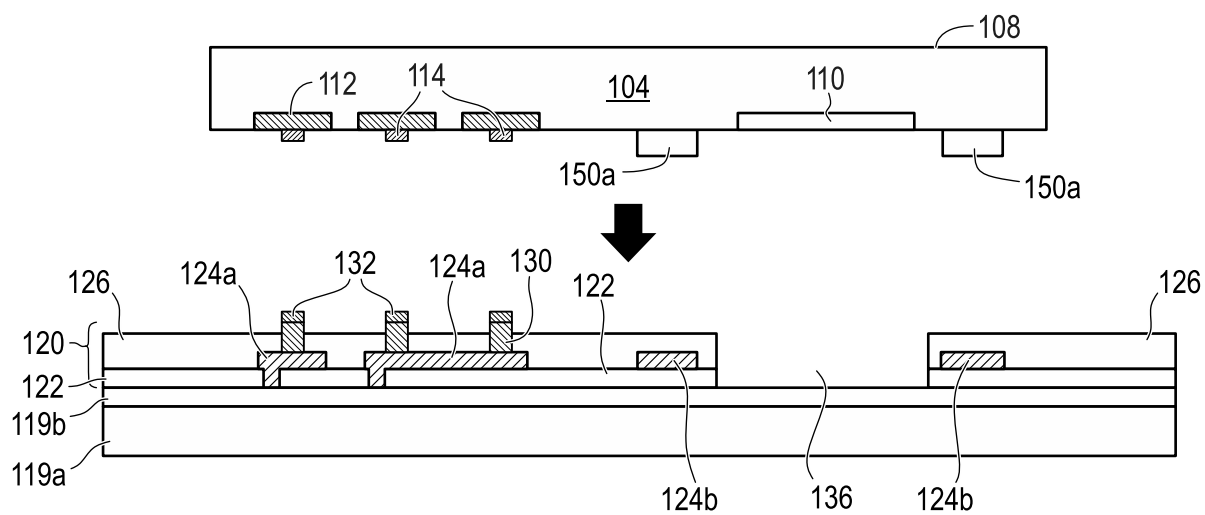


FIG. 3a

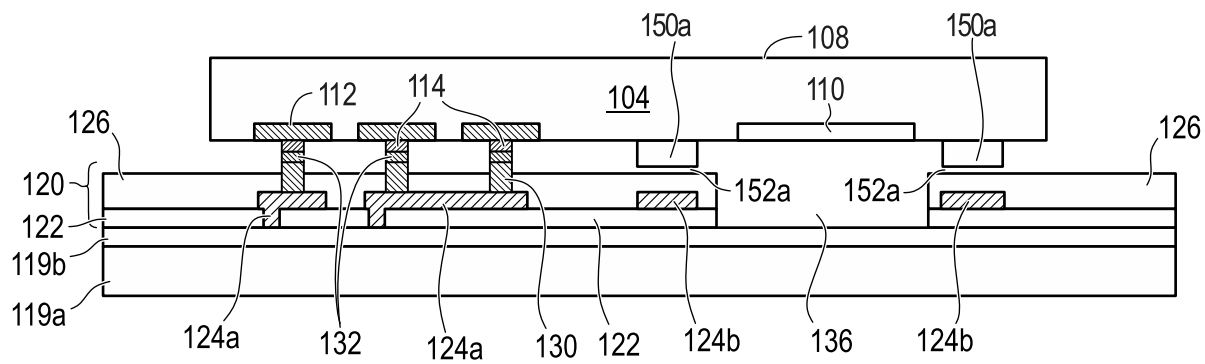


FIG. 3b

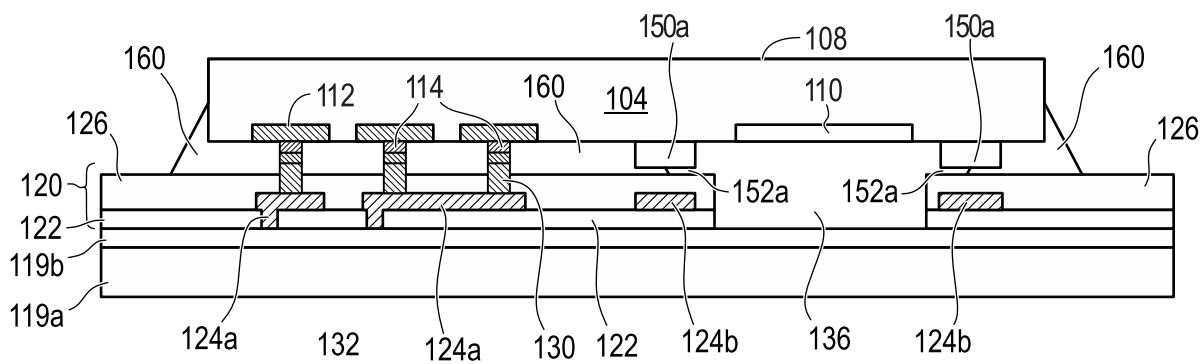


FIG. 3c

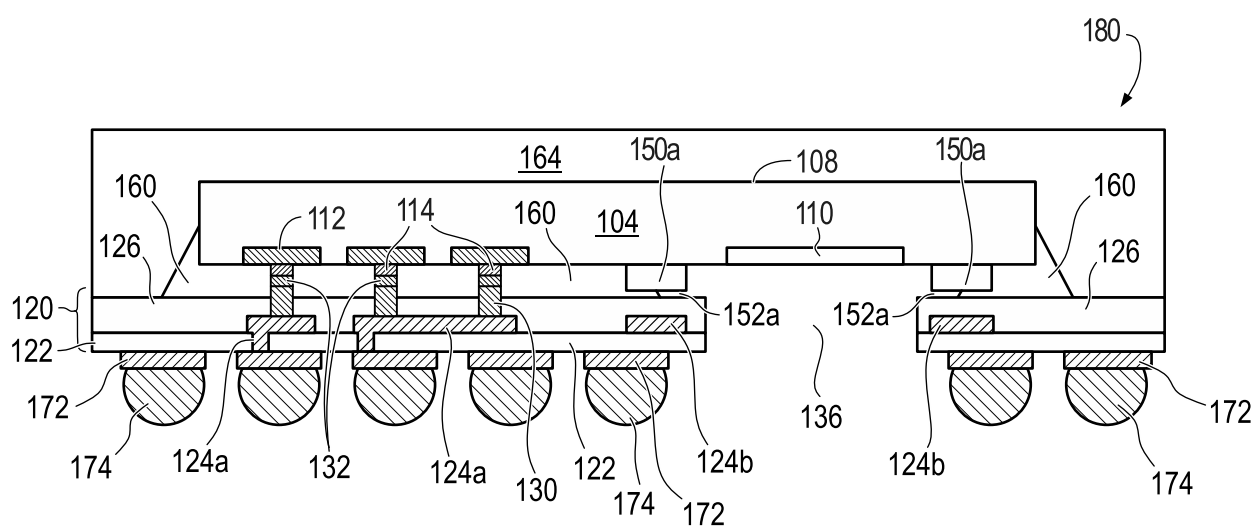


FIG. 3d

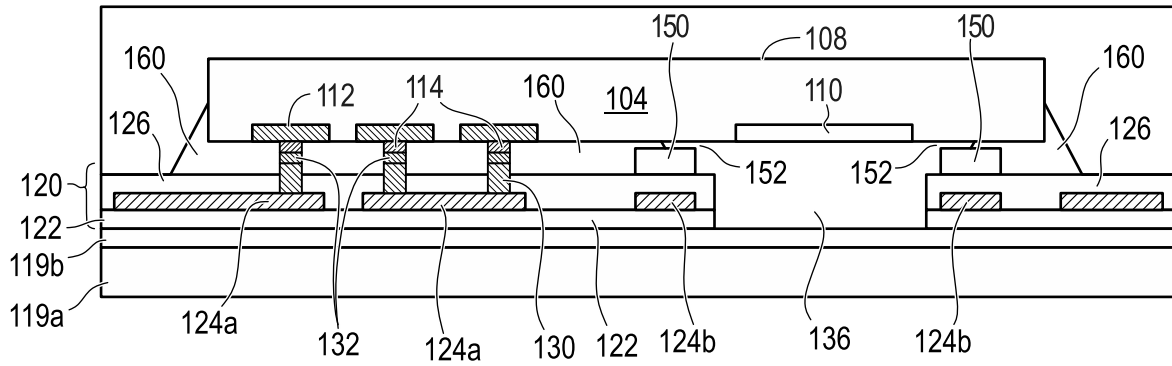


FIG. 4a

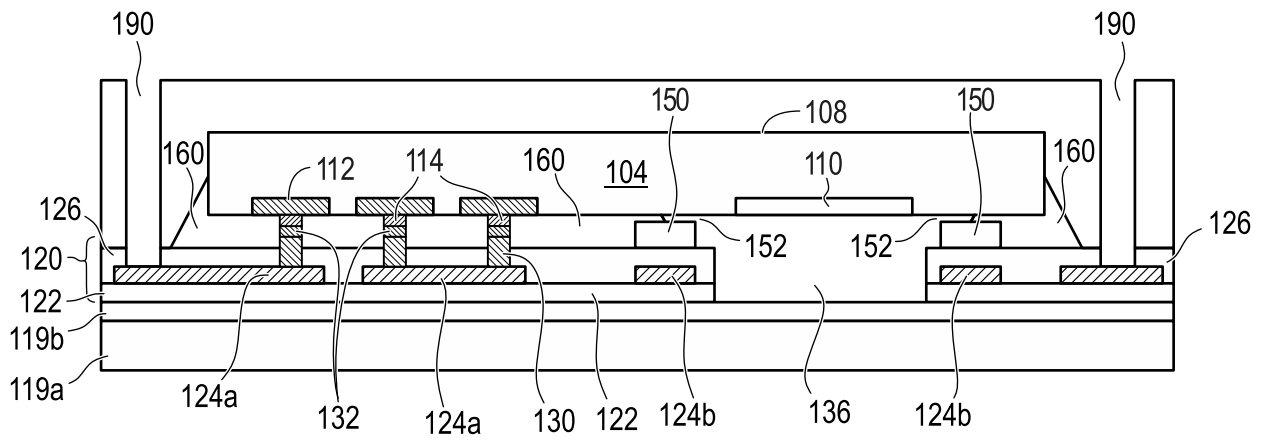


FIG. 4b

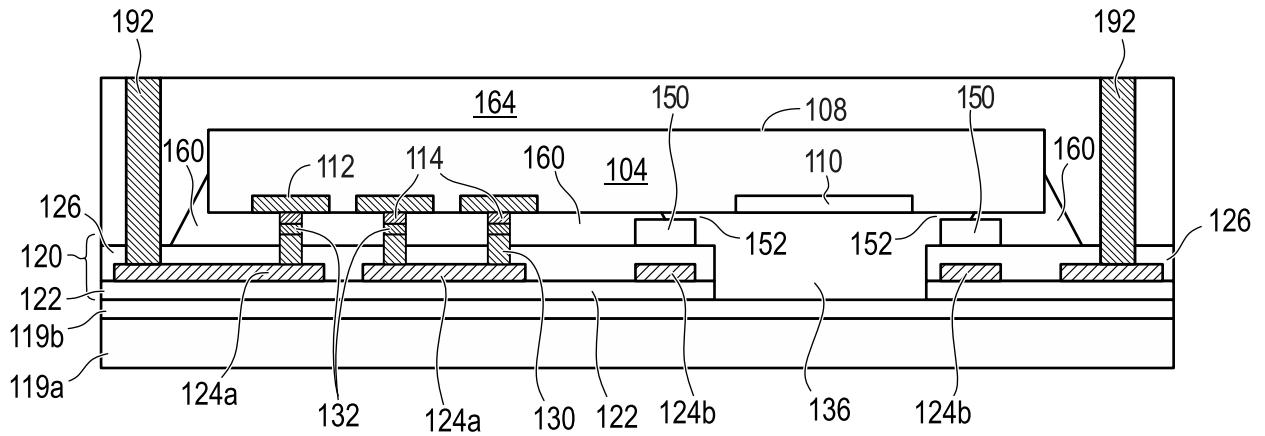


FIG. 4c

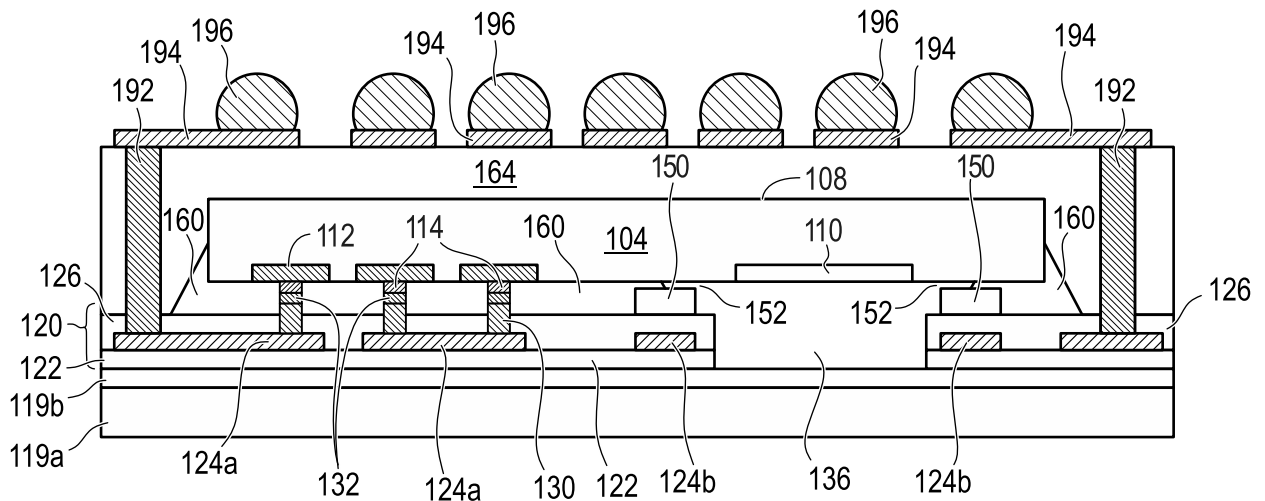


FIG. 4d

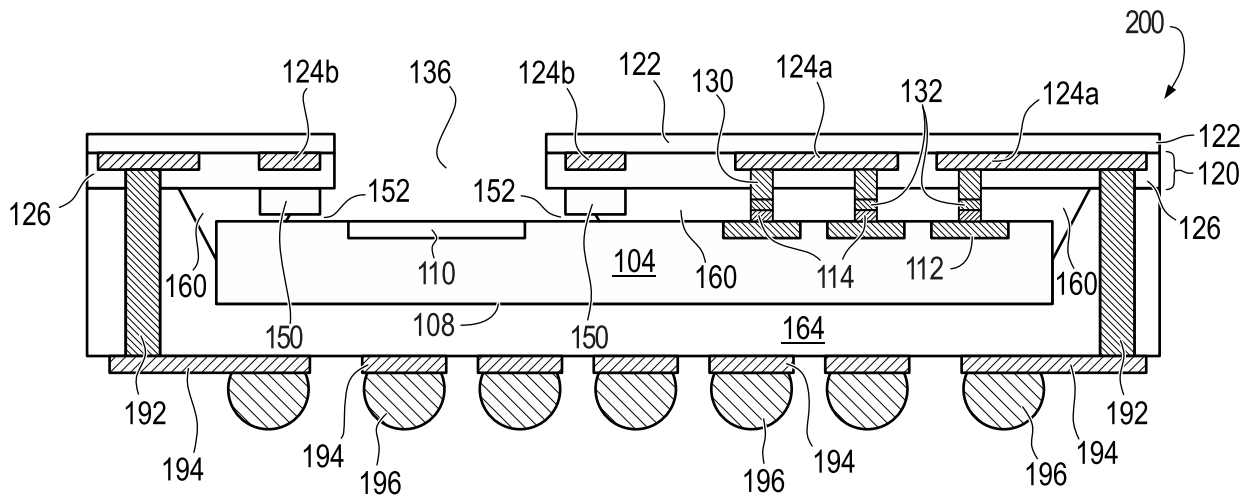


FIG. 4e

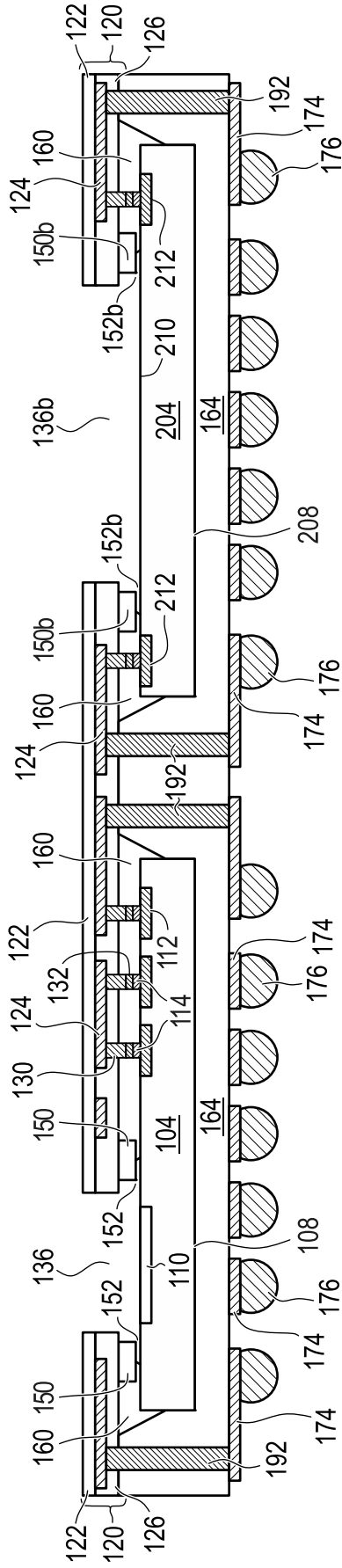


FIG. 5a

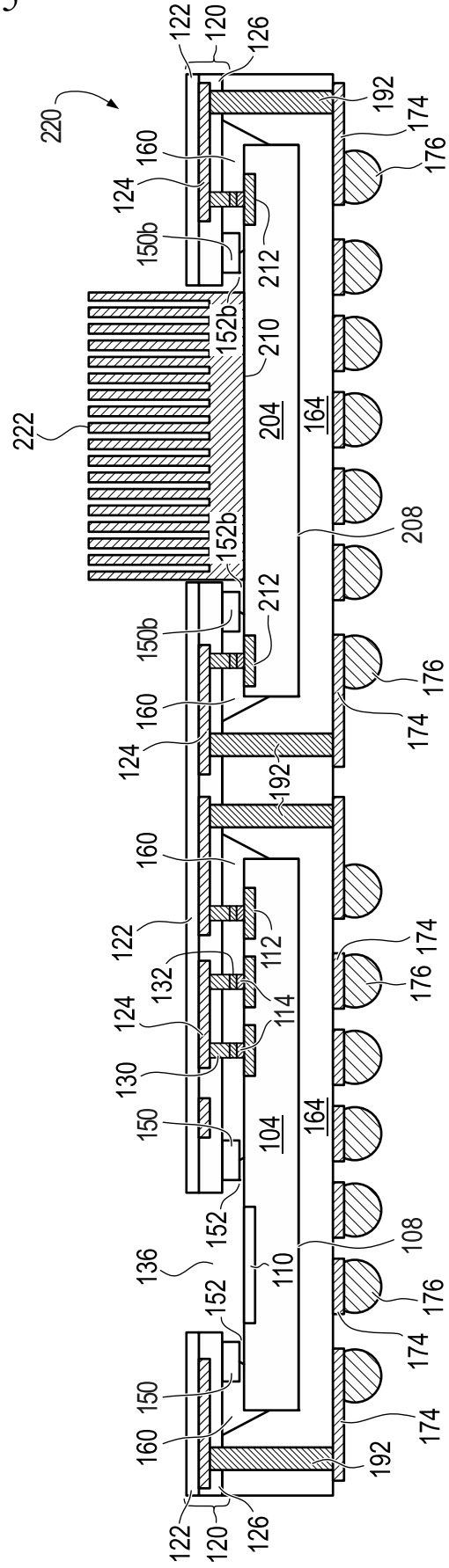


FIG. 5b

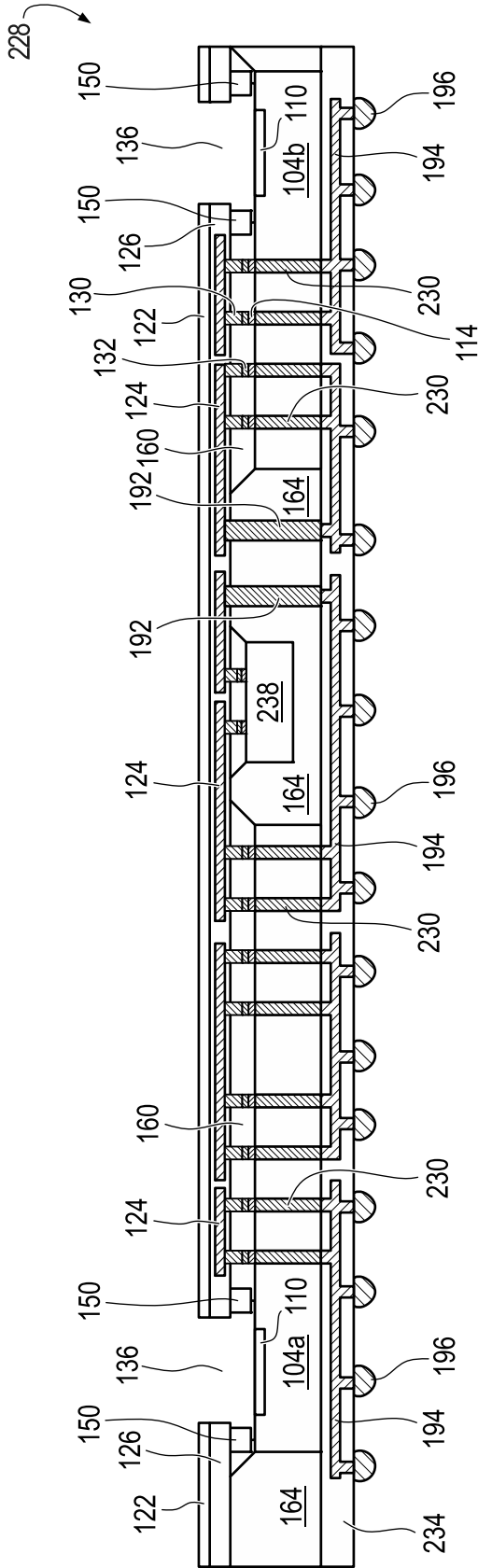
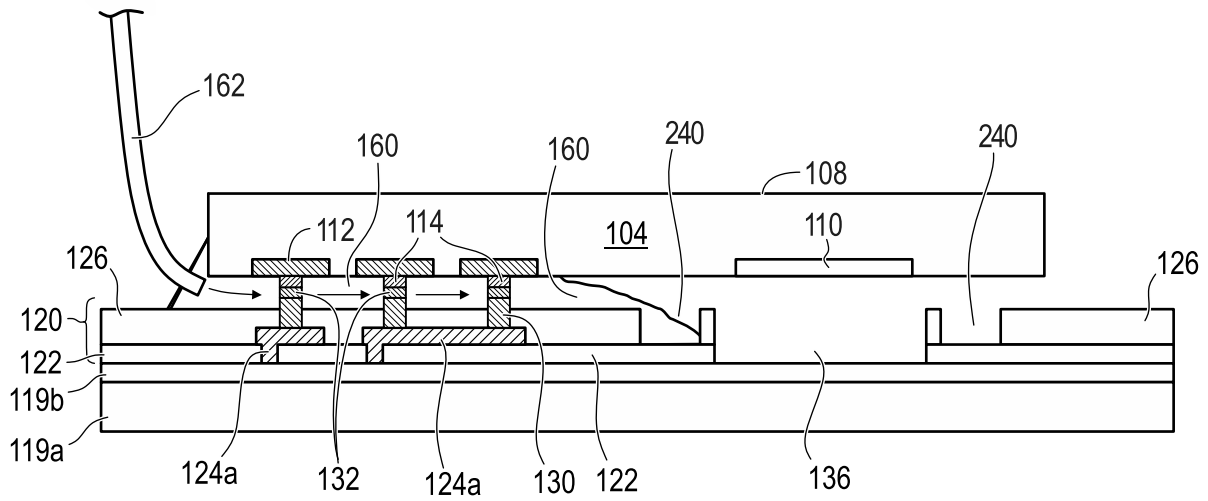
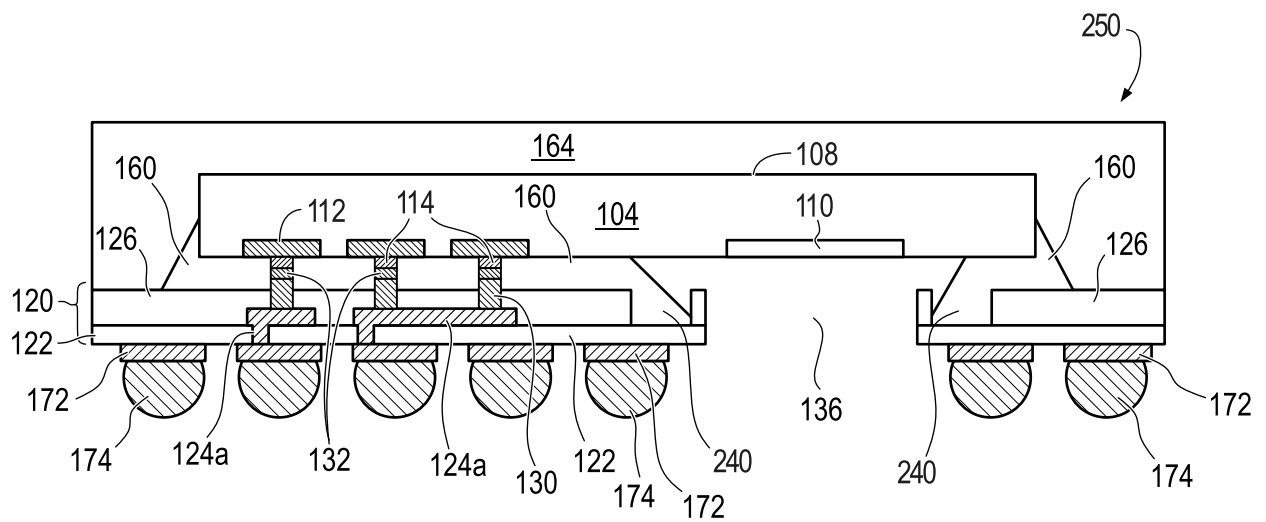


FIG. 6



*FIG. 7a*



*FIG. 7b*

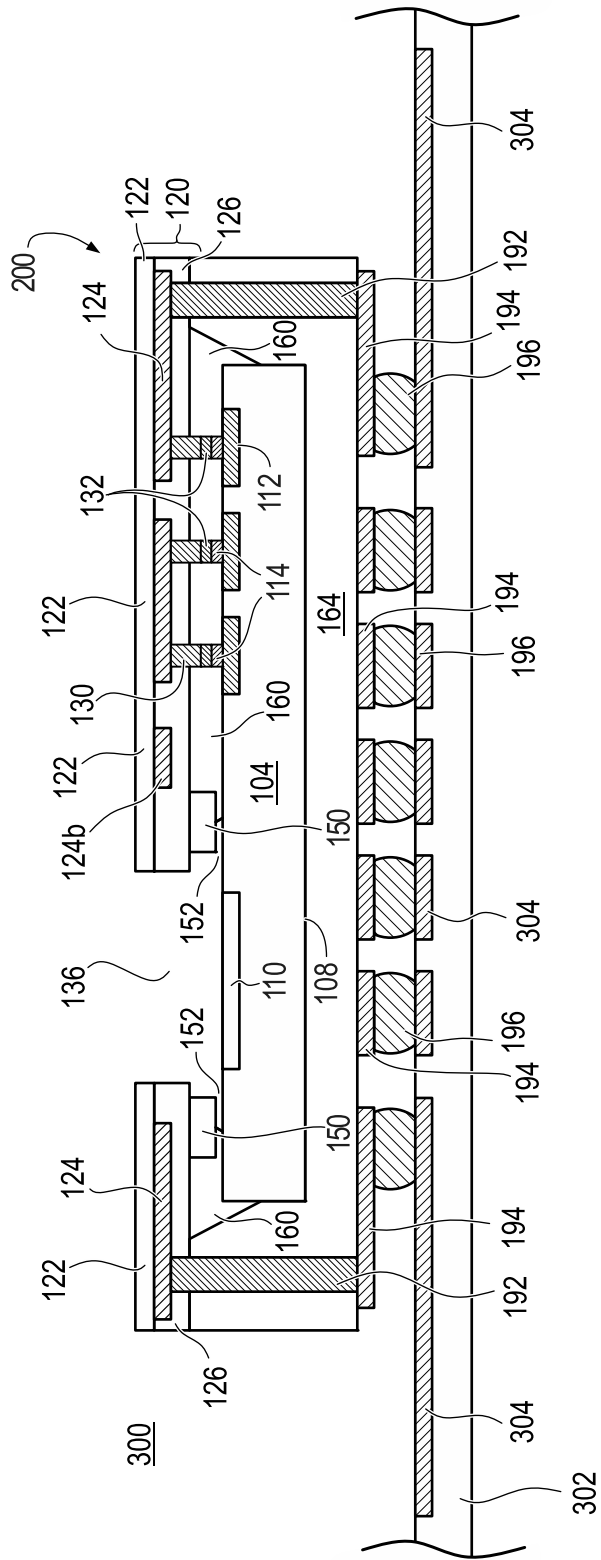


FIG. 8a

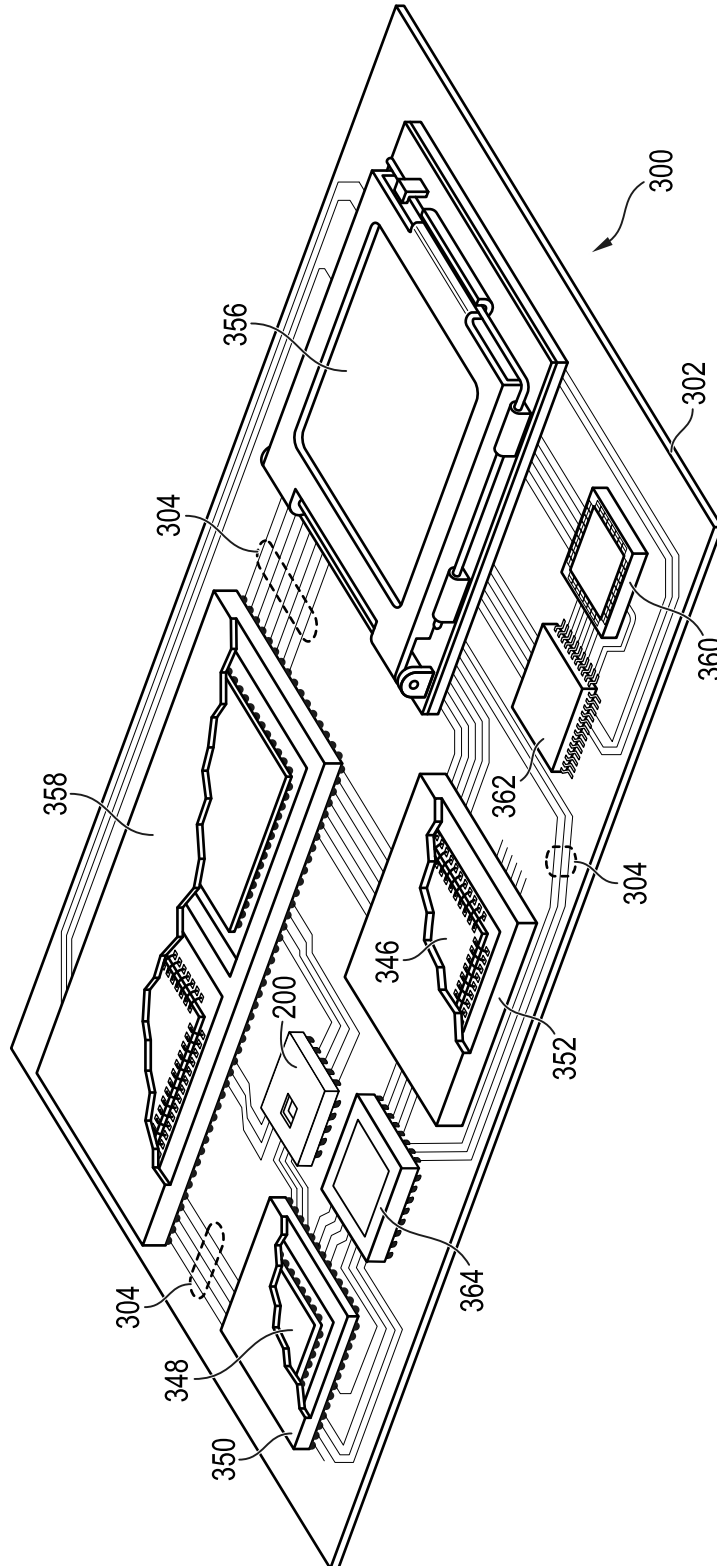


FIG. 8b